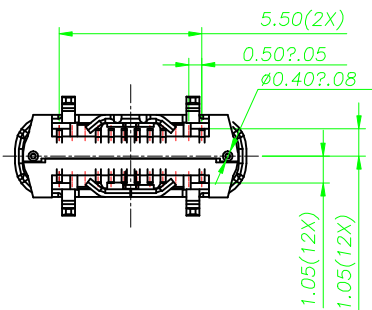
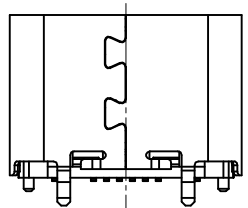
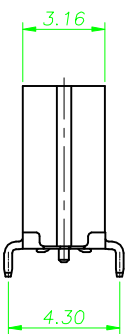
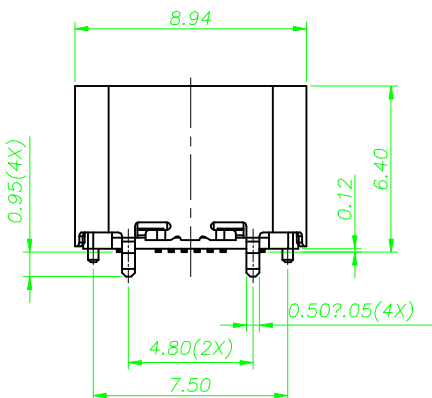
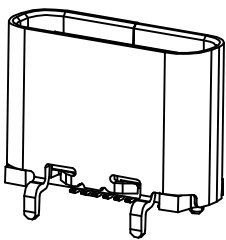
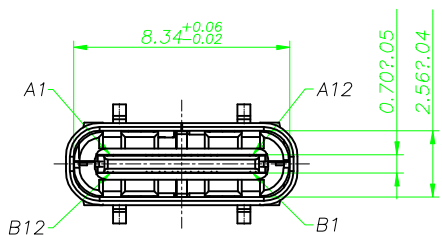


RoHS 客户图

目錄 MAPX	提交內容 MODIFICATION	日期 DATE
A0	NEW	09-10-20



NOTE:  
 1.MATERIAL SPECIFICATION:  
 1.HOUSING:LCP,UL94 V-0.  
 2.TERMINAL: COPPER ALLOY(C1814)  
 3.MID PLATE: STAINLESS STEEL(SUS301)  
 4.FRONT SHELL: STAINLESS STEEL(SUS304)  
 2.PLATING SPECIFICATION:  
 2-1.TERMINAL:  
 Ni 50u" MIN. UNDER PLATED OVER ALL.  
 Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.  
 (GOLD PLATING THICKNESS FOLLOW THE P/N)  
 PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N  
 2-2.FRONT SHELL:  
 Ni 50u" MIN. UNDER PLATED OVER ALL.  
 2-3.MID PLATE:  
 CLEAR ONLY  
 3.MECHANICAL PERFORMANCE,  
 3-1.INSERTION FORCE: 0.5~2.0kgf.  
 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.  
 3-3.DURABILITY: 10000 CYCLES.  
 4.ELECTRICAL PERFORMANCE,  
 4-1. VOLTAGE RATING:5 V DC/AC (RMS. max)  
 CURRENT RATING:5 AMPS. FOR TOTAL VBUS/GND PINS;  
 1.25AMPS FOR CC PIN,0.25 AMPS. FOR ALL OTHER CONTACT.  
 4-2. LLCR:  
 VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.  
 SHIELD: 50mΩ/MAX.  
 LLCR MAX. CHANGE OF ALL PINS: 10mΩ.  
 4-3.INSULATION RESISTANCE: 100MΩ MIN  
 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.  
 5. ENVIRONMENTAL PERFORMANCE:  
 OPERATING TEMPERATURE: -25℃~+85℃.  
 6.IR REFLOW:  
 THE PEAK TEMPERATURE ON THE BOARD SHALL  
 BE MAINTAINED FOR 10 SECONDS AT 260°C.

产品图 PRODUCT CHART DWG		深圳市精拓金电子有限公司					
公差一览表 TOLERANCE UNLESS OTHERWISE		单位 UNITS	MM	制图 DRAWING	杨政林	产品料号 PRODUCT PART NO.	
X	±0.30	X'	±5'	比例 SCALE	1:1	审核 CHKD	郭治富
.X	±0.25	.X'	±2'				
.XX	±0.30	.XX'	±1'	日期 DATE	2009/10/20	核准 APPD	黄国荣
.XXX	±0.15	.XXX'	±0.5'				
		角法 VIEW	角法	版本 VER	A0	TYPE C 16P母座180度SMT H=6.5	